IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Leonard Forbes et al.

Title:

STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

Docket No.:

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Pamela Perkins

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Mail Stop Issue Fee

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following:

- Authorization to charge Deposit 19-0743 in the amount of \$1440.00 to cover the Large Entity Issue Fee X Payment
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this day of September, 2008.